

MA3S1330G

Silicon epitaxial planar type

For switching circuits

■ Features

- Two isolated elements contained in one package, allowing high-density mounting
- Two diodes are connected in series in the package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

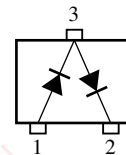
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current	Single	I_F	100
	Series		65
Peak forward current	Single	I_{FM}	200
	Series		130
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Package

- Code
SSMini3-F3
- Pin Name
1: Anode 1
2: Cathode 2
3: Cathode 1
Anode 2

■ Marking Symbol: MP

■ Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100\text{ mA}$			1.2	V
Reverse voltage	V_R	$I_R = 100\ \mu\text{A}$	80			V
Reverse current	I_R	$V_R = 75\text{ V}$			100	nA
Terminal capacitance	C_t^{*1}	$V_R = 0\text{ V}, f = 1\text{ MHz}$			5.5	pF
	C_t^{*2}				3.0	
Reverse recovery time ^{*3}	t_{rr}^{*1}	$I_F = 10\text{ mA}, V_R = 6\text{ V}$			150	ns
	t_{rr}^{*2}	$I_{rr} = 0.1 I_R, R_L = 100\ \Omega$			9	

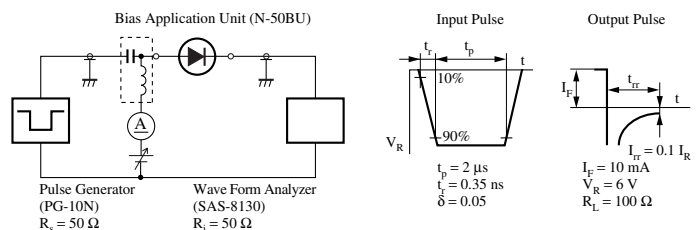
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

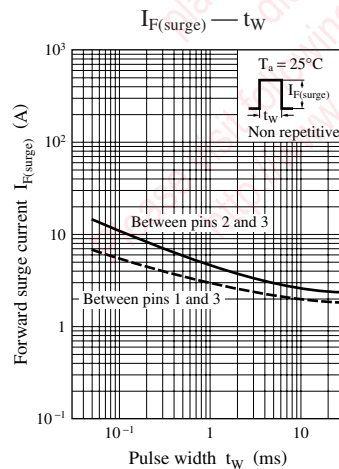
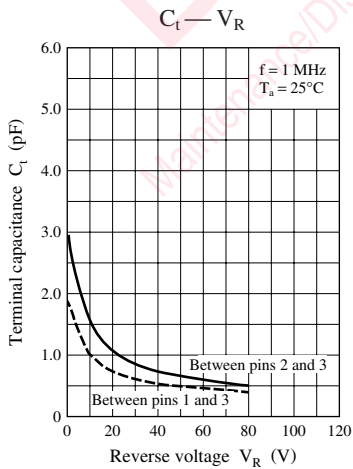
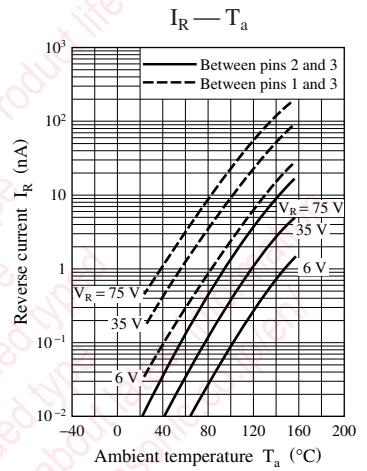
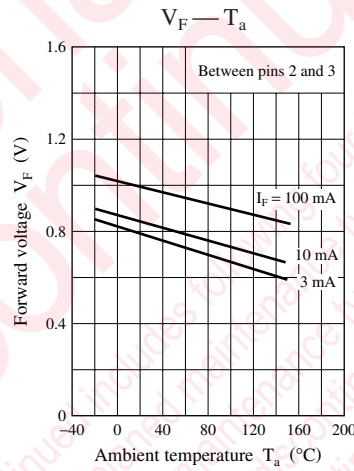
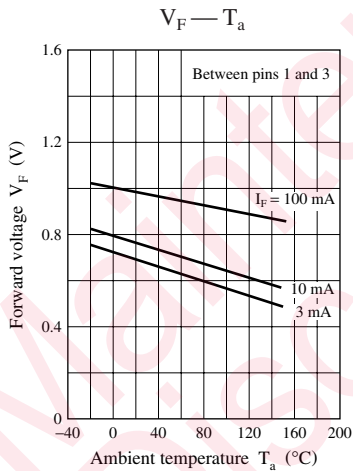
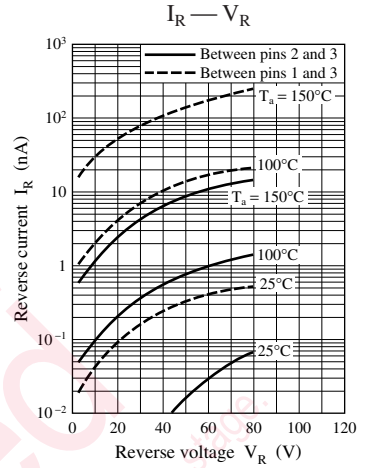
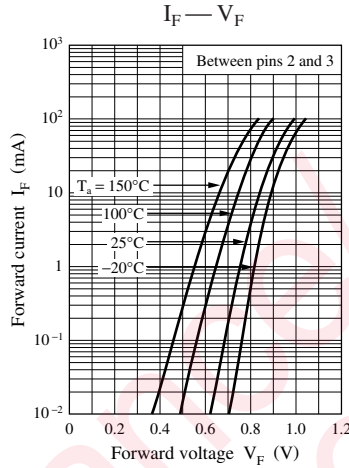
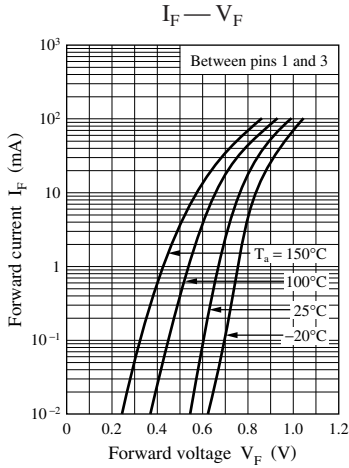
2. Absolute frequency of input and output is 100 MHz.

3. *1: Between pins 2 and 3

*2: Between pins 1 and 3

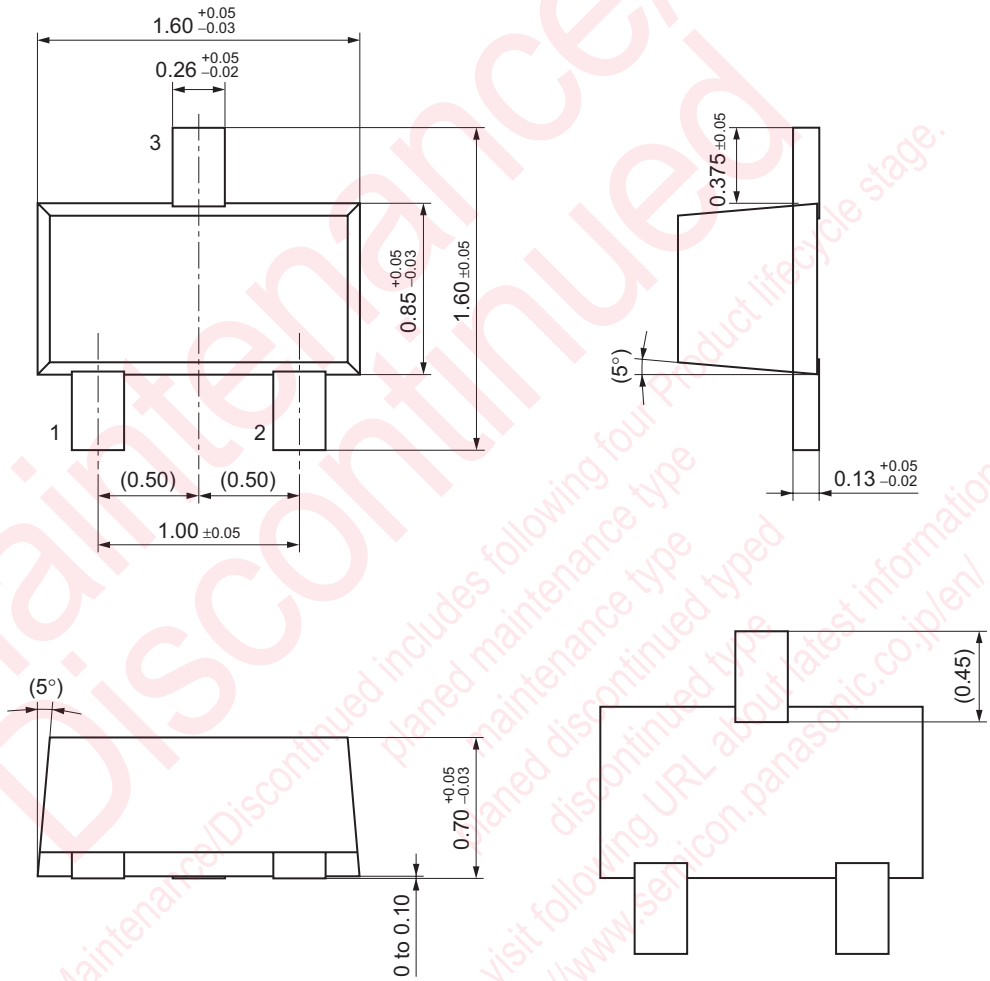
*3: t_{rr} measurement circuit





SSMini3-F3

Unit: mm



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